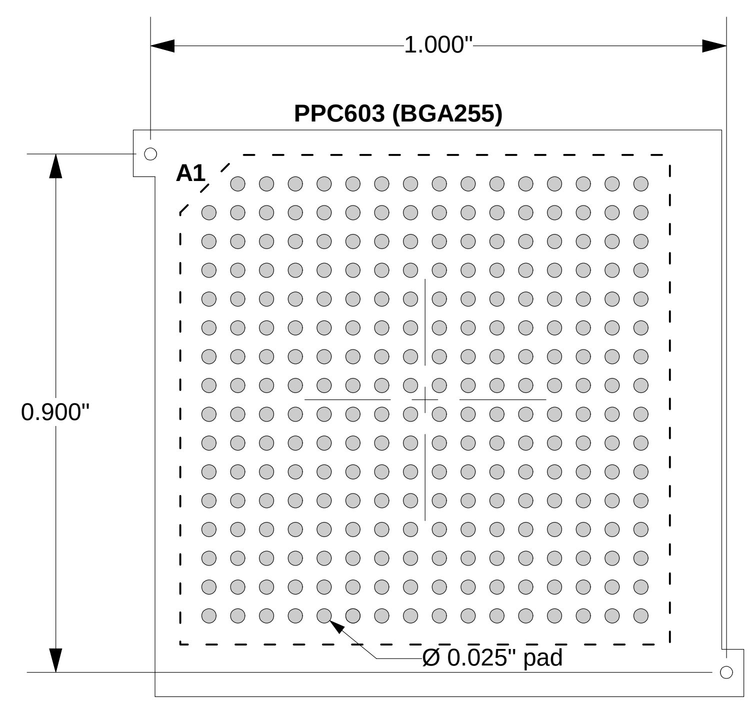
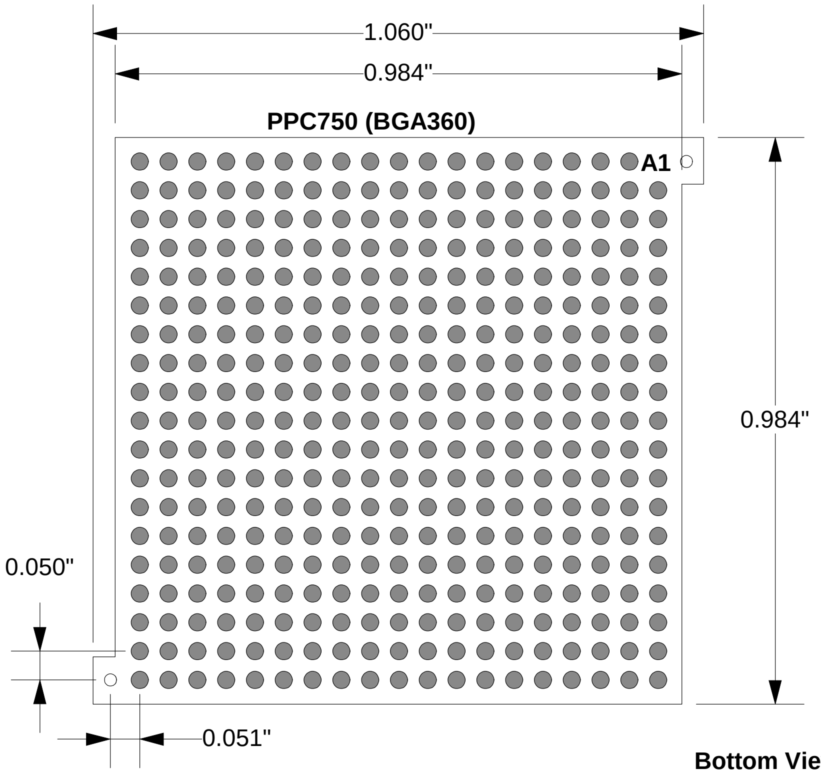
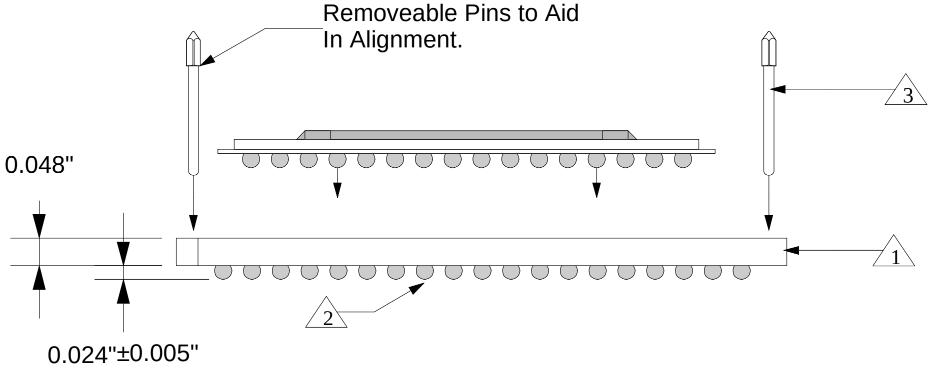




Top View

Bottom View



Side View

1. Substrate: 0.0480"±0.007" FR4/G10 or equivalent high temp material. 1/2 oz. Cu clad. SnPb plating
2. Balls: Eutectic 63/37 SnPb.
3. Removeable Alignment Pins: Material- Brass Alloy 360 1/2 hard; finish- 10µ" Au over 50µ" Ni (min.).

Description: Device Convertor

255 position BGA surface mount land pattern (0.05" pitch, 16 x 16 array) to 360 position BGA balls (0.05" pitch, 19x19 array) with removeable alignment pins. The adapter makes the conversion from a PPC 603 to a PPC 750. The adapter is 55 Ohm ± 10% controlled impedance.

DC-BGA/BGA-750-S-B-02 Drawing	Status: Released	Scale 3:1	Rev: A
 PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Drawing: M. Gilk	Date: 3/12/99	
	File: DC-BGA/BGA-750-S-B-02 Dwg	Modified:	

All tolerances: ±0.005" (unless stated otherwise). Materials and specifications are subject to change without notice.